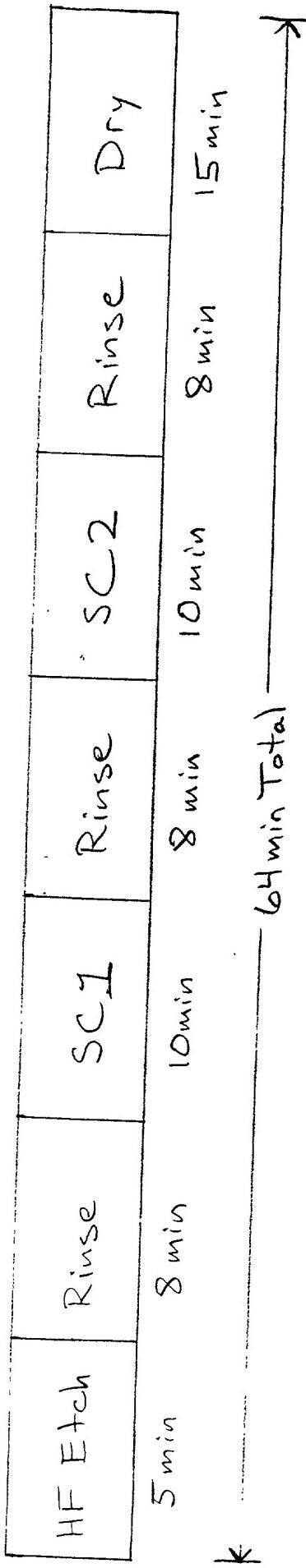
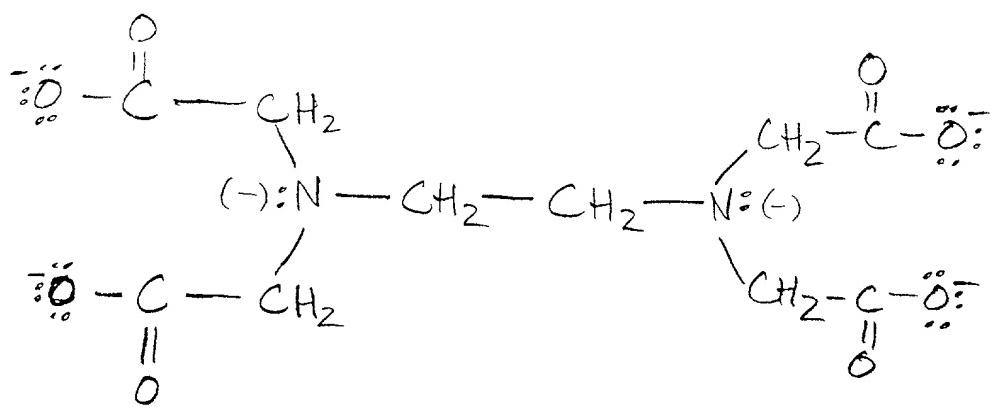


Figure 1 a Wet Bench: oxide etch + hydrophilic clean (RCA clean)



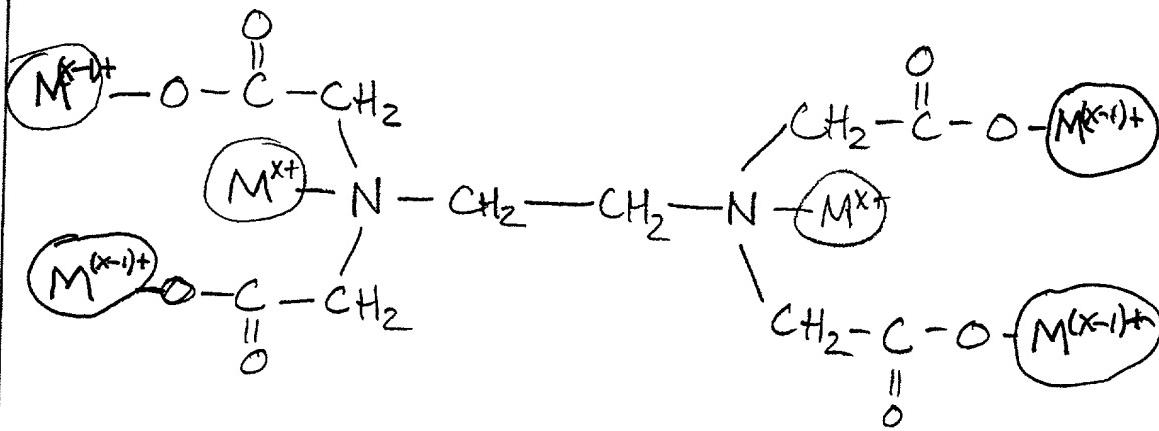
Single Wafer Cleaning Tool Single Step Clean
Oxide etch + hydrophilic clean

Figure 2 a



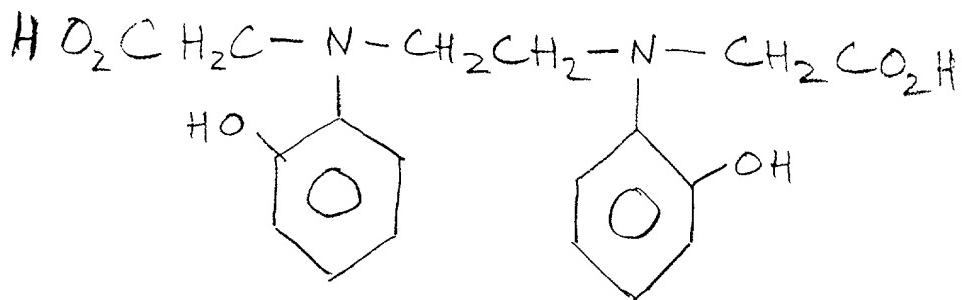
↓ Binds Metal ions

Figure 2 b



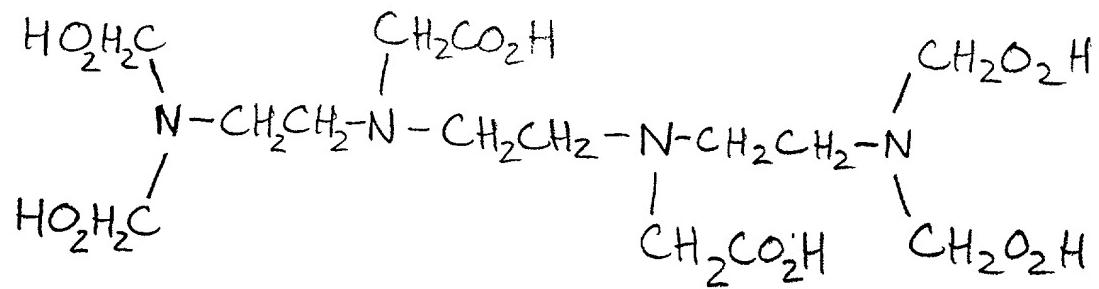
(HPED)

Figure 3a



(TTHA)

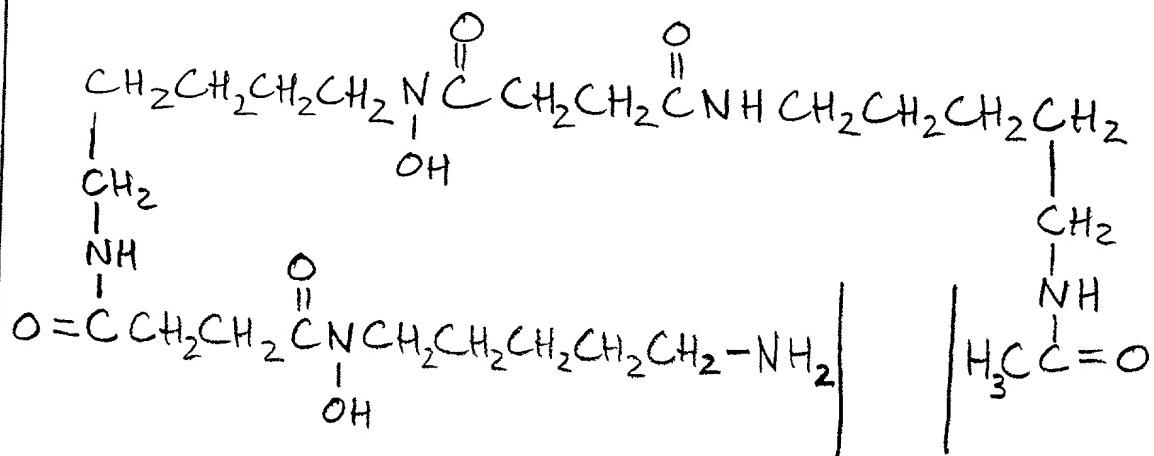
Figure 3b



卷之三

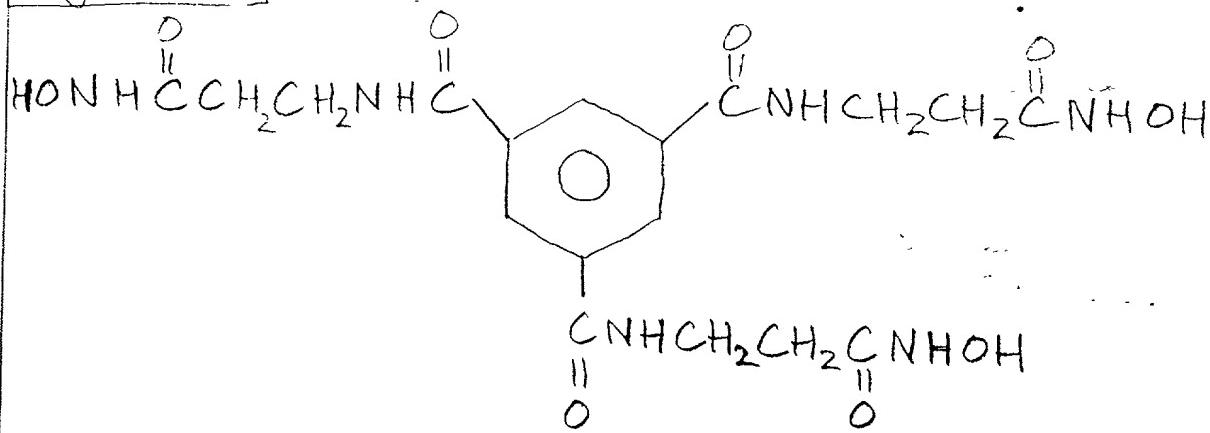
Figure 3c

Desferriferrioxamin B



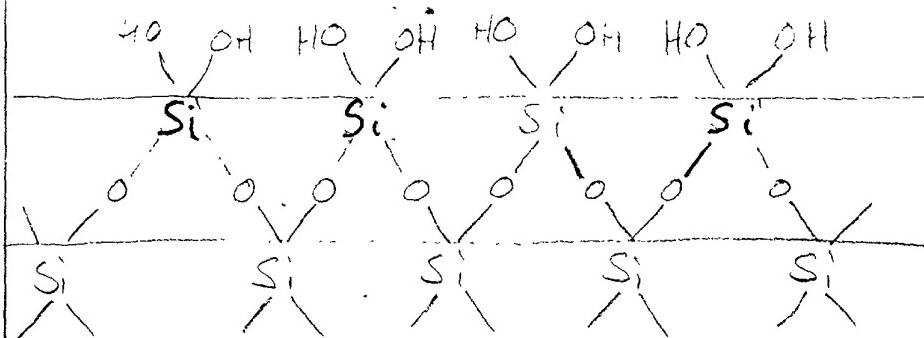
BAMFPH)

Figure 3.d



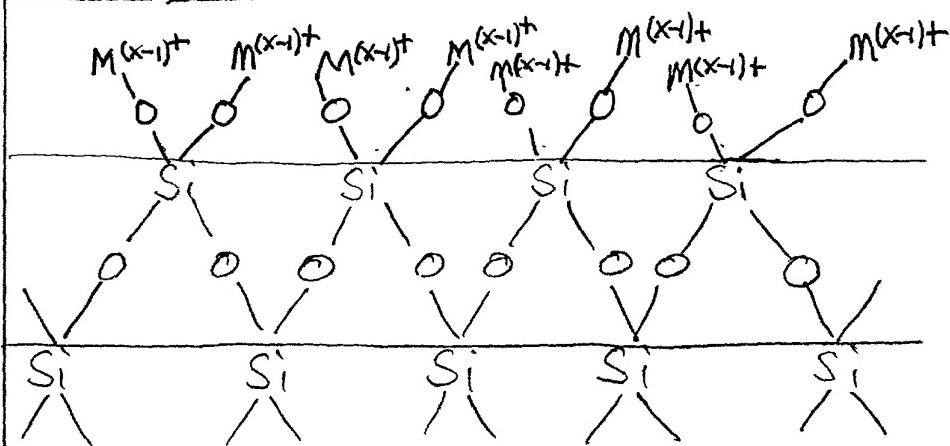
Intuition on characterization

Figure 4 a



Hydroxide
terminated
 SiO_2 film

Figure 4 b



Chemisorption

Fig. 5

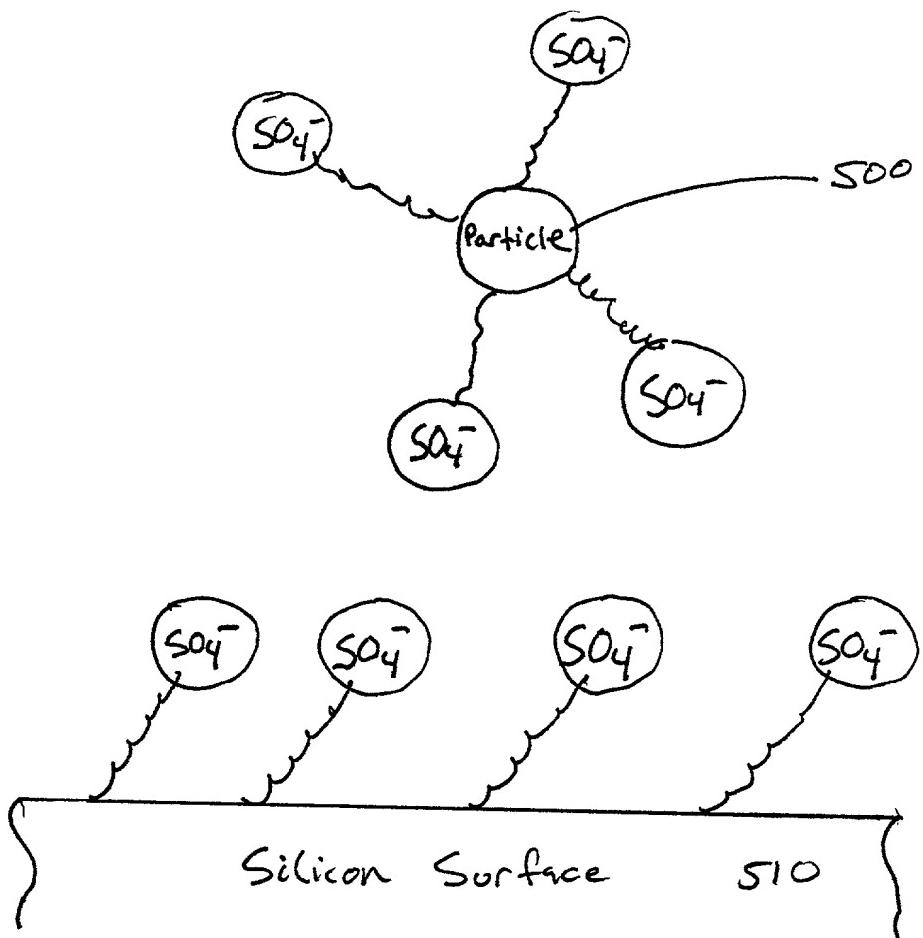


Figure 6a

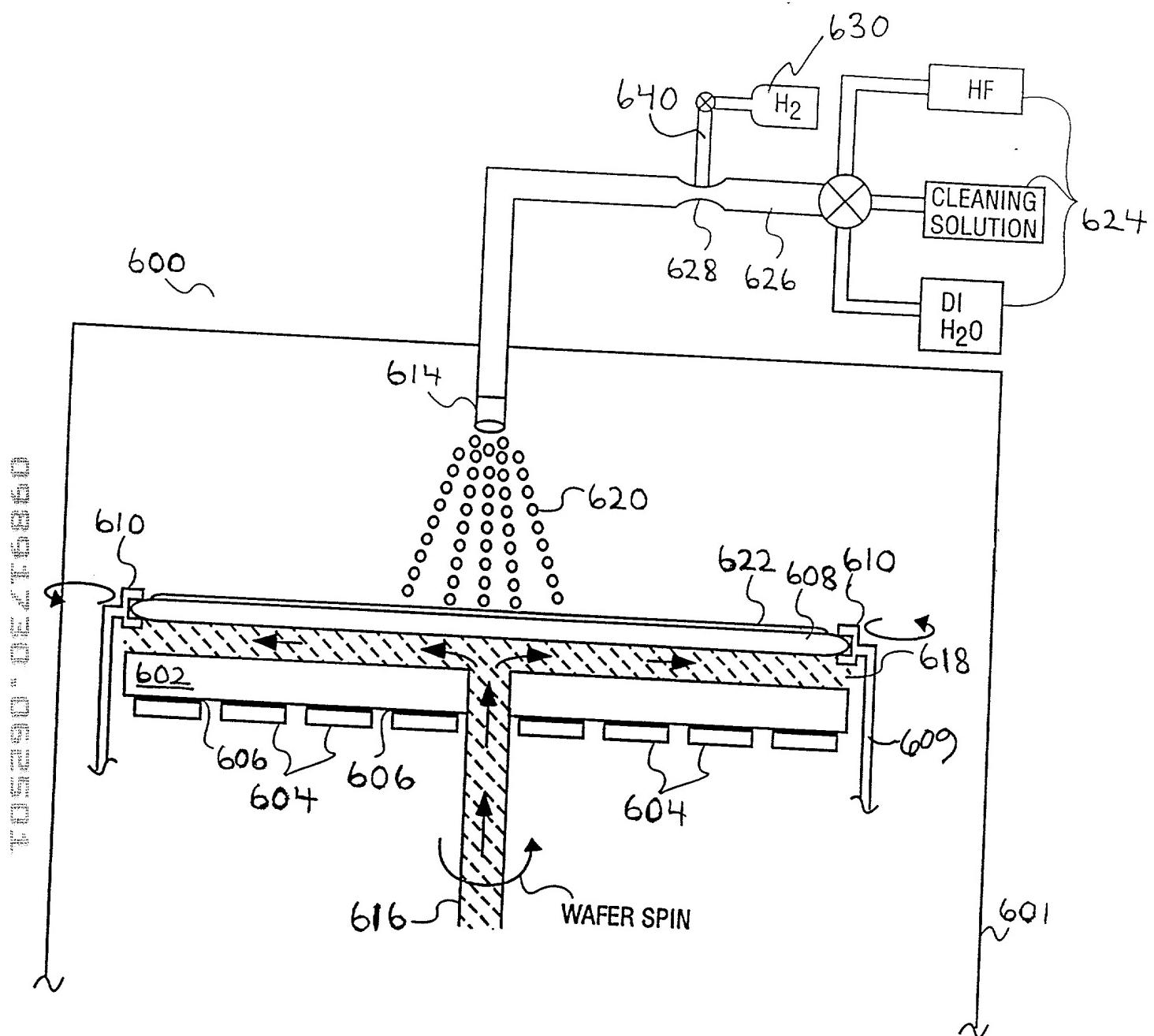


Figure 6b

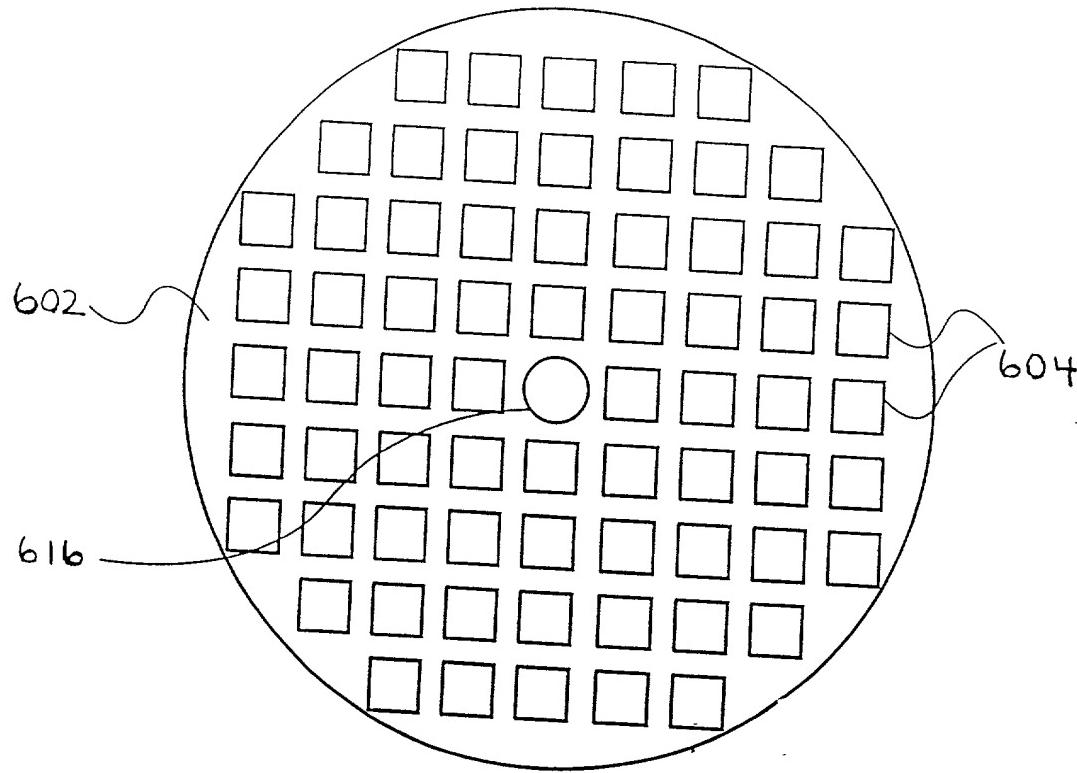


Figure 6c

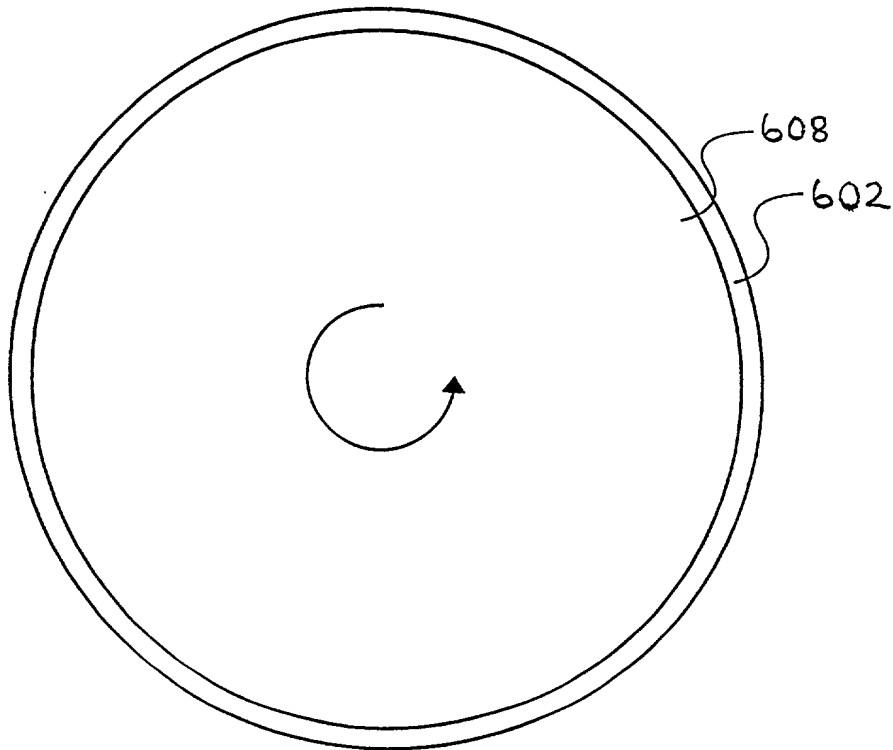


Figure 6d

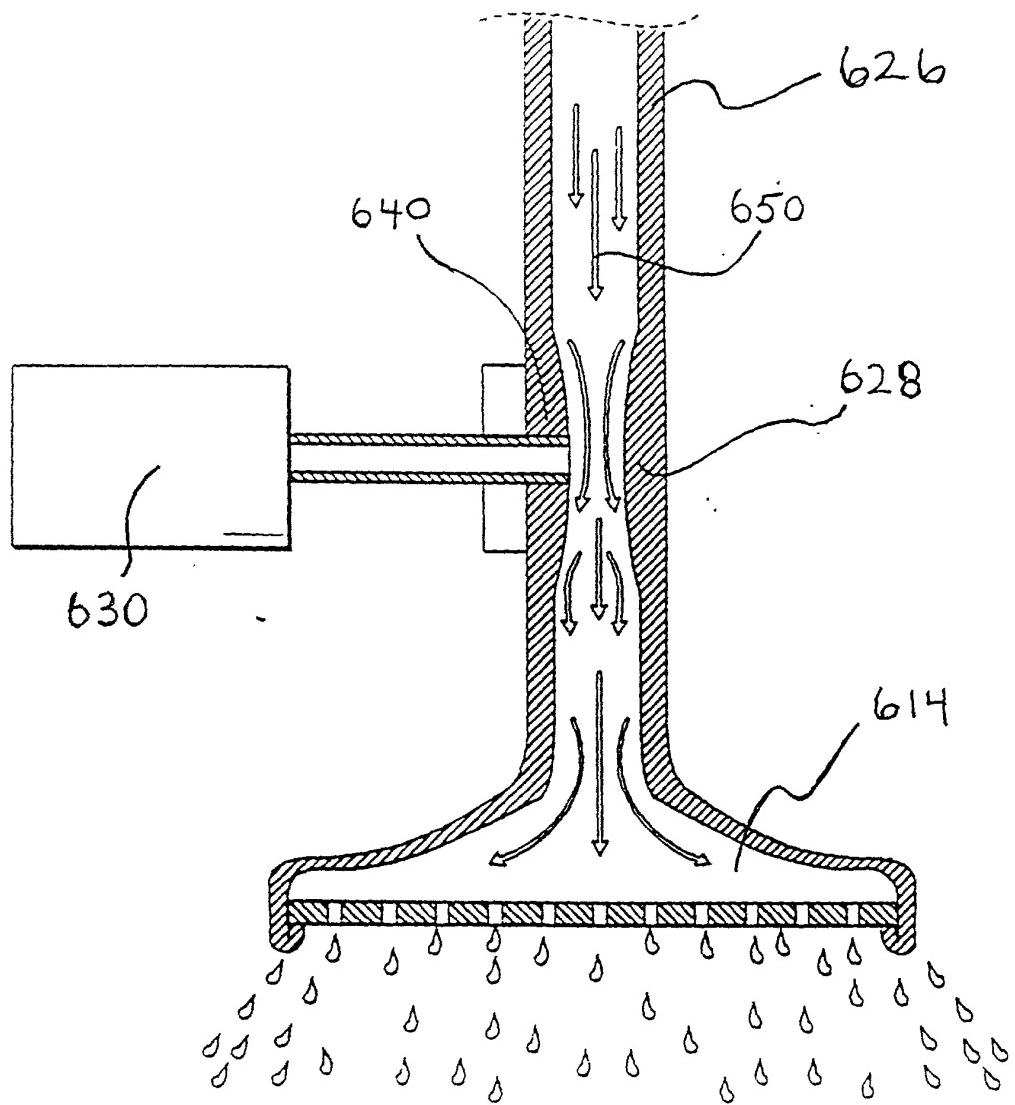


FIGURE 7a

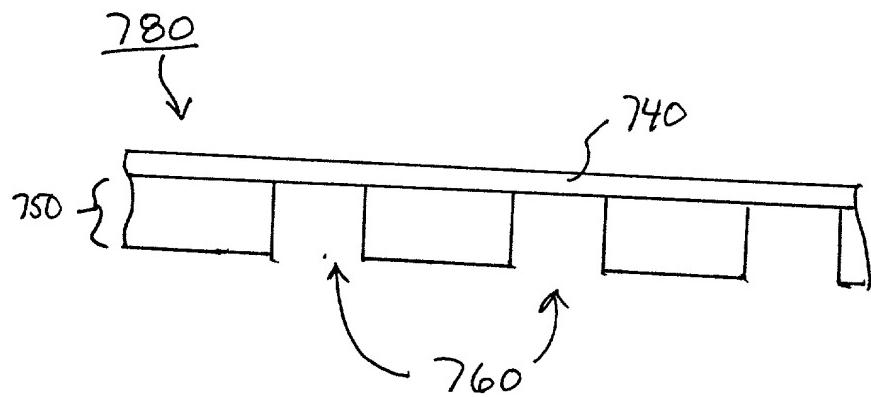
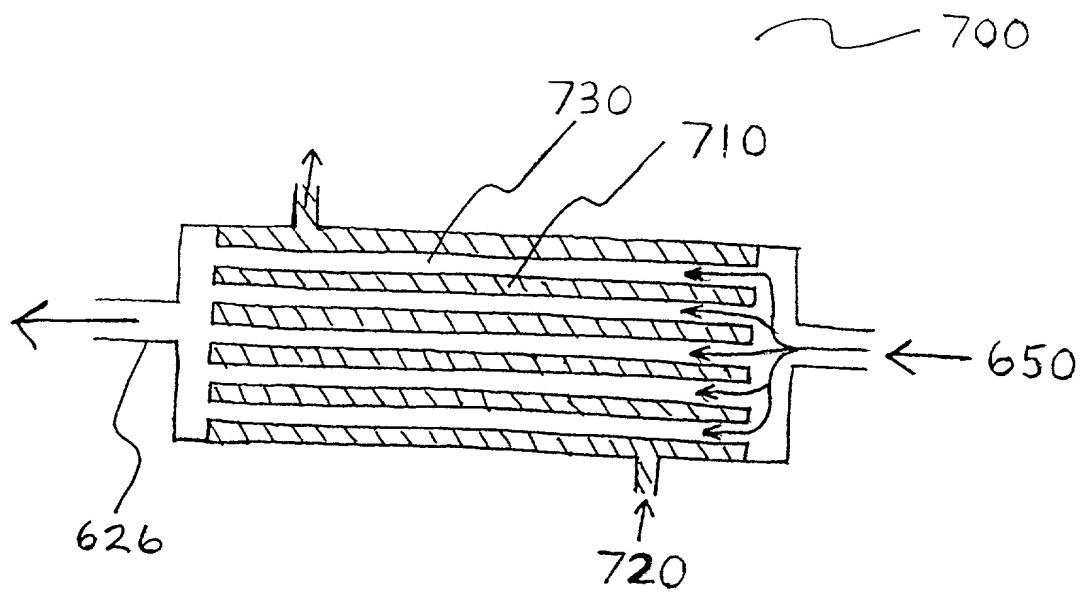


Fig. 7b

Figure 7c

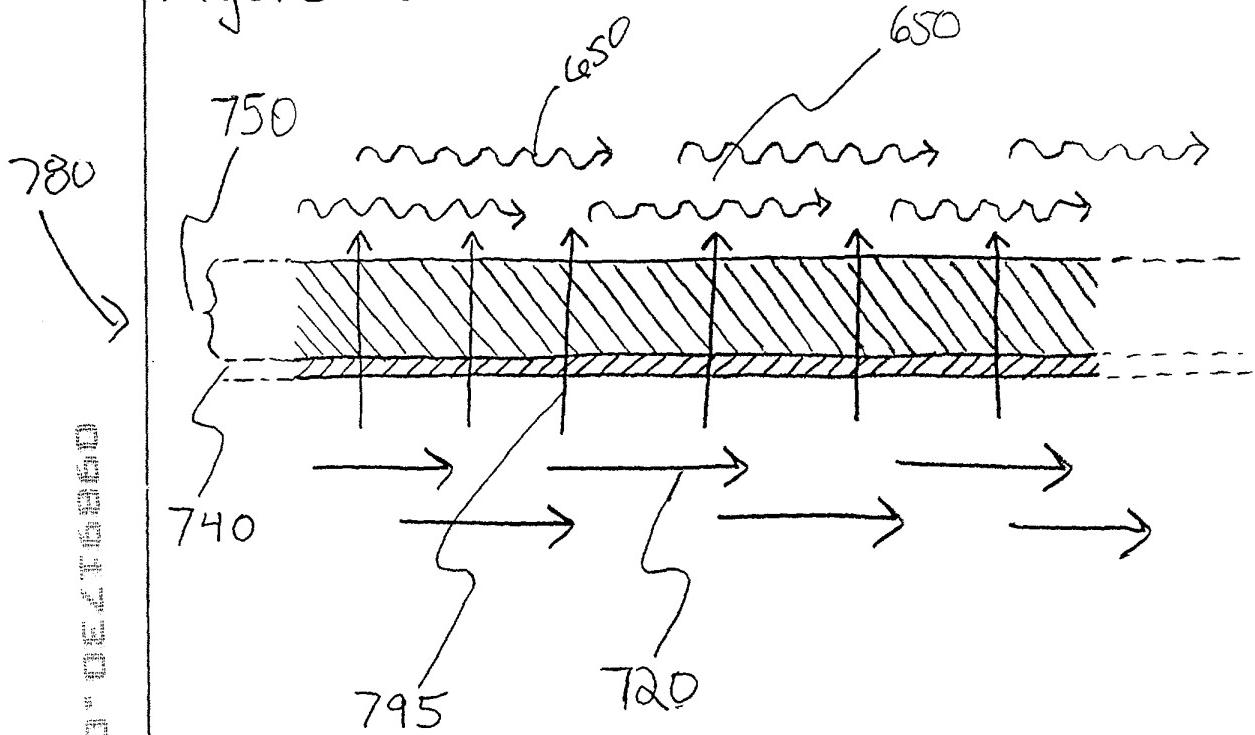


Fig. 8

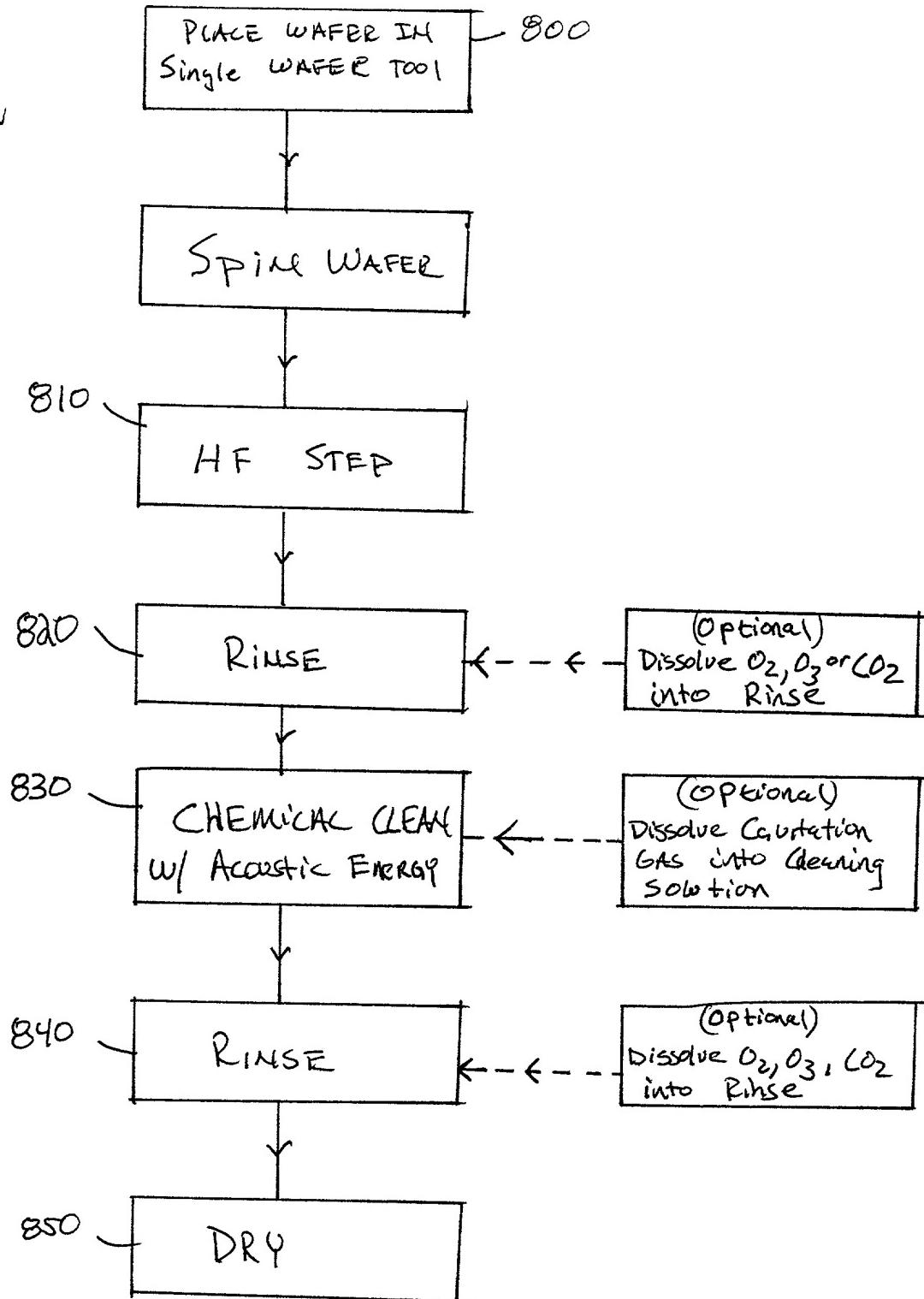
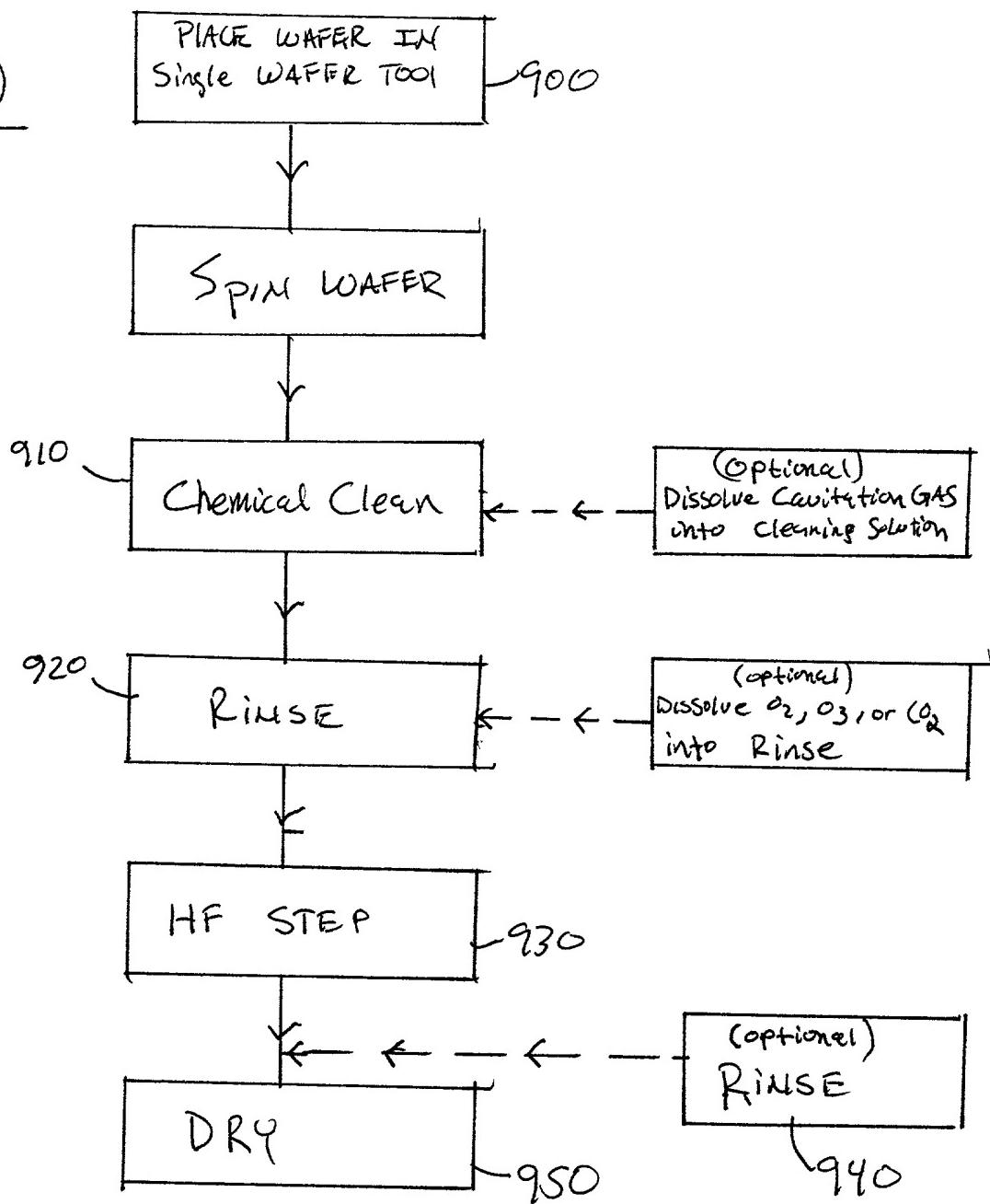


FIG. 9



HF etch diagram

Figure 10a

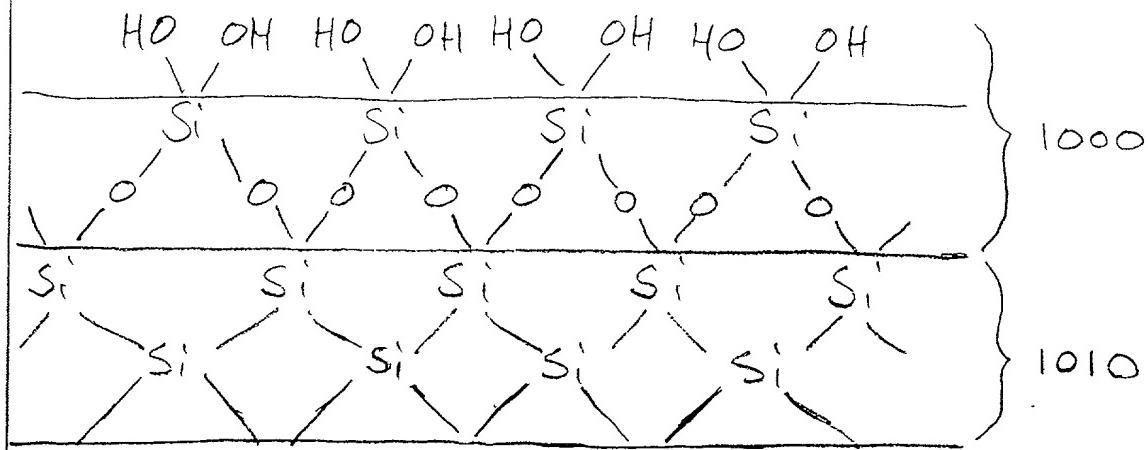


Figure 10b Hydrophobic Surface

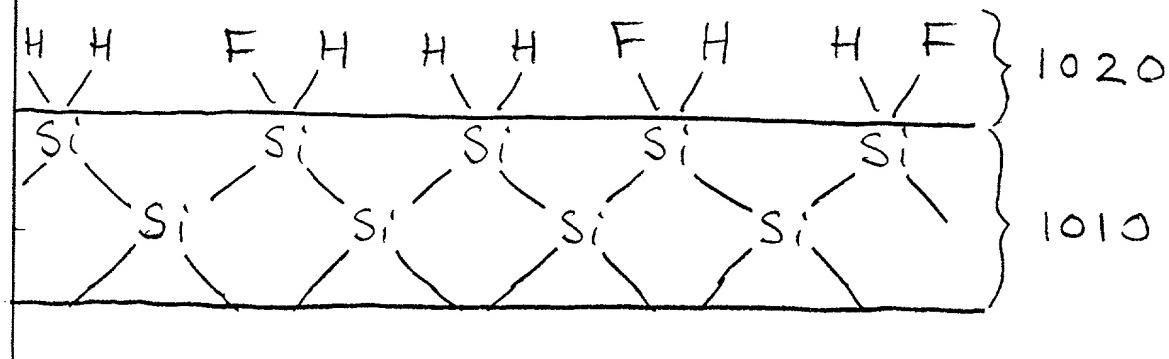


Fig 11

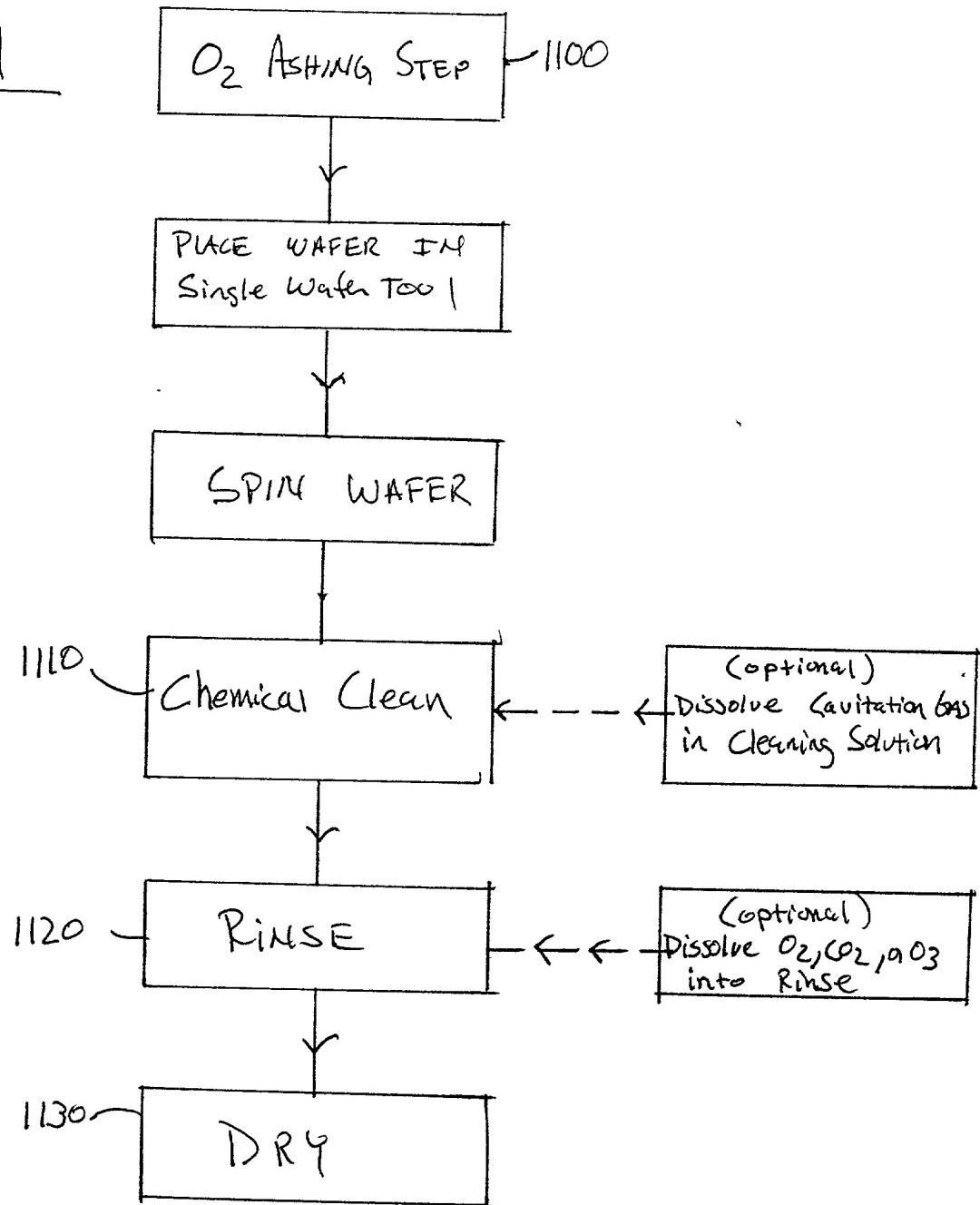
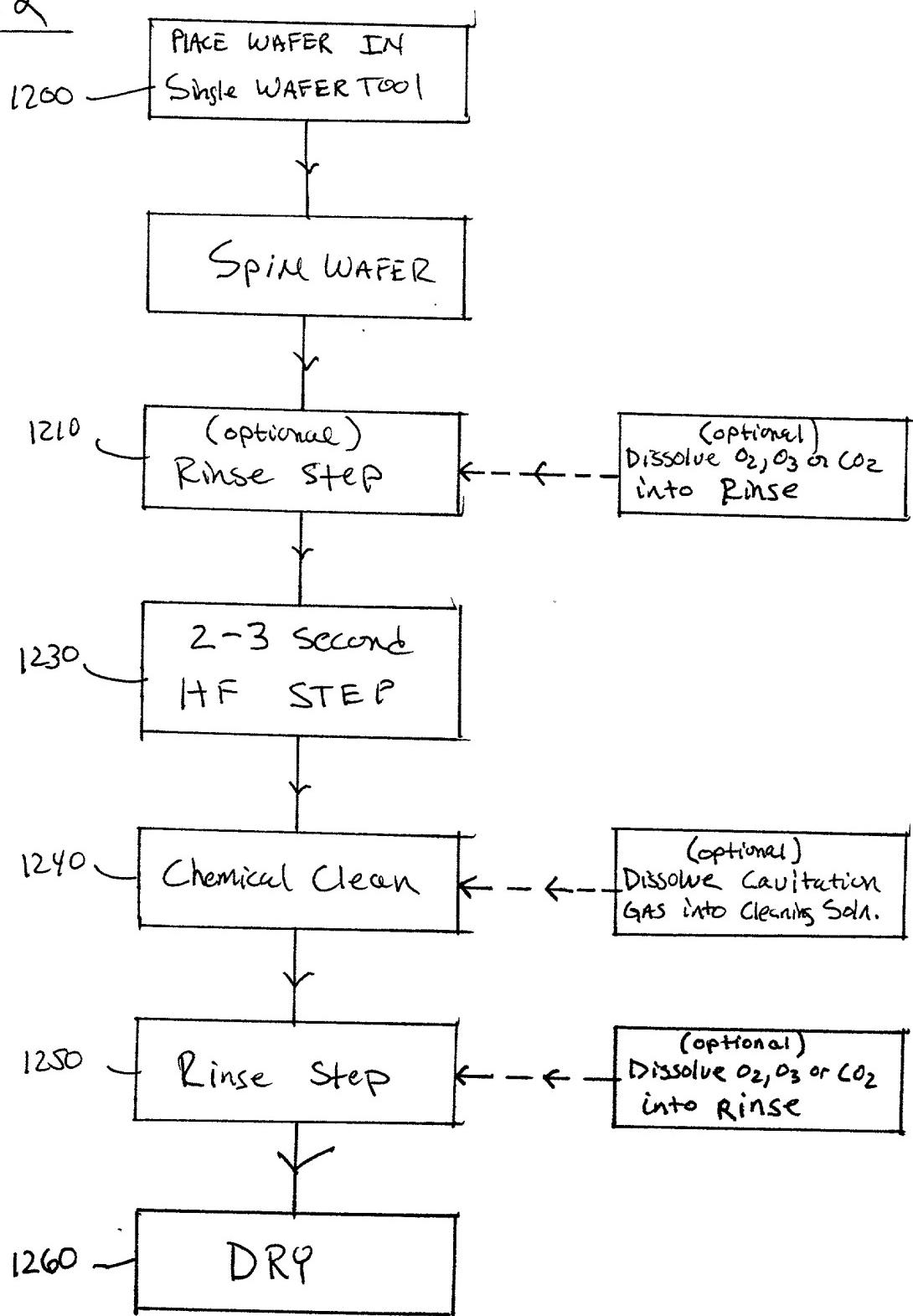


Fig. 12



Sucit + F Wave Diagram

FIGURE 13a

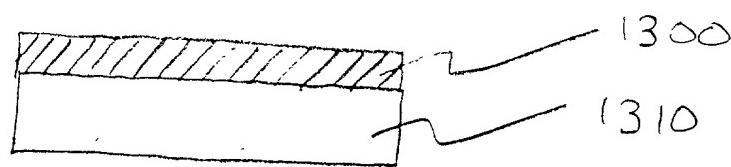


FIGURE 13b

